



November 2015

# FOD814 Series, FOD817 Series 4-Pin DIP Phototransistor Optocouplers

## Features

- AC Input Response (FOD814)
- Current Transfer Ratio in Selected Groups:
  - FOD814: 20–300%
  - FOD817: 50–600%
  - FOD814A: 50–150%
  - FOD817A: 80–160%
  - FOD817B: 130–260%
  - FOD817C: 200–400%
  - FOD817D: 300–600%
- Minimum  $BV_{CEO}$  of 70 V Guaranteed
- Safety and Regulatory Approvals
  - UL1577, 5,000  $VAC_{RMS}$  for 1 Minute
  - DIN EN/IEC60747-5-5

## Applications

### FOD814 Series

- AC Line Monitor
- Unknown Polarity DC Sensor
- Telephone Line Interface

### FOD817 Series

- Power Supply Regulators
- Digital Logic Inputs
- Microprocessor Inputs

## Description

The FOD814 consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a silicon phototransistor output in a 4-pin dual in-line package. The FOD817 Series consists of a gallium arsenide infrared emitting diode driving a silicon phototransistor in a 4-pin dual in-line package.

## Functional Block Diagram

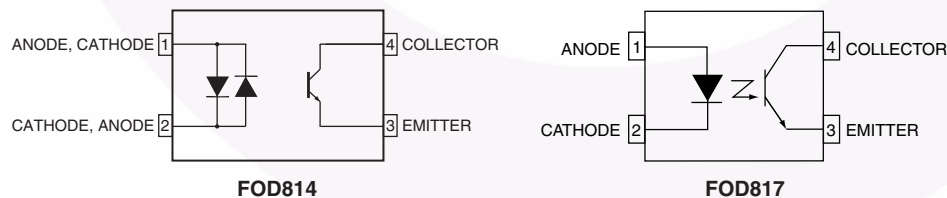


Figure 1. Schematic

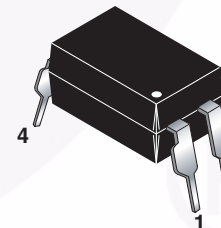


Figure 2. Package Outlines

## Safety and Insulation Ratings

As per DIN EN/IEC 60747-5-5, this optocoupler is suitable for “safe electrical insulation” only within the safety limit data. Compliance with the safety ratings shall be ensured by means of protective circuits.

| Parameter   |                        | Characteristics |
|---|------------------------|-----------------|
| Installation Classifications per DIN VDE 0110/1.89 Table 1, For Rated Mains Voltage | < 150 V <sub>RMS</sub> | I–IV            |
|   | < 300 V <sub>RMS</sub> | I–III           |
| Climatic Classification   |                        | 30/110/21       |
| Pollution Degree (DIN VDE 0110/1.89)  |                        | 2               |
| Comparative Tracking Index  |                        | 175             |

| Symbol                | Parameter  | Value              | Unit              |
|-----------------------|--|--------------------|-------------------|
| V <sub>PR</sub>       | Input-to-Output Test Voltage, Method A, V <sub>IORM</sub> × 1.6 = V <sub>PR</sub> , Type and Sample Test with t <sub>m</sub> = 10 s, Partial Discharge < 5 pC  | 1360               | V <sub>peak</sub> |
|                       | Input-to-Output Test Voltage, Method B, V <sub>IORM</sub> × 1.875 = V <sub>PR</sub> , 100% Production Test with t <sub>m</sub> = 1 s, Partial Discharge < 5 pC | 1560               | V <sub>peak</sub> |
| V <sub>IORM</sub>     | Maximum Working Insulation Voltage   | 850                | V <sub>peak</sub> |
| V <sub>IOTM</sub>     | Highest Allowable Over-Voltage   | 8000               | V <sub>peak</sub> |
|                       | External Creepage  | ≥ 7                | mm                |
|                       | External Clearance   | ≥ 7                | mm                |
|                       | External Clearance (for Option W, 0.4" Lead Spacing)   | ≥ 10               | mm                |
| DTI                   | Distance Through Insulation (Insulation Thickness)   | ≥ 0.4              | mm                |
| T <sub>S</sub>        | Case Temperature <sup>(1)</sup>  | 175                | °C                |
| I <sub>S,INPUT</sub>  | Input Current <sup>(1)</sup>   | 400                | mA                |
| P <sub>S,OUTPUT</sub> | Output Power <sup>(1)</sup>  | 700                | mW                |
| R <sub>IO</sub>       | Insulation Resistance at T <sub>S</sub> , V <sub>IO</sub> = 500 V <sup>(1)</sup>   | > 10 <sup>11</sup> | Ω                 |

**Note:**

1. Safety limit values – maximum values allowed in the event of a failure.

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^\circ\text{C}$  Unless otherwise specified.

| Symbol              | Parameter                           | Value              |             | Unit                      |
|---------------------|-------------------------------------|--------------------|-------------|---------------------------|
|                     |                                     | FOD814             | FOD817      |                           |
| <b>Total Device</b> |                                     |                    |             |                           |
| $T_{STG}$           | Storage Temperature                 | -55 to +150        |             | $^\circ\text{C}$          |
| $T_{OPR}$           | Operating Temperature               | -55 to +105        | -55 to +110 | $^\circ\text{C}$          |
| $T_J$               | Junction Temperature                | -55 to +125        |             | $^\circ\text{C}$          |
| $T_{SOL}$           | Lead Solder Temperature             | 260 for 10 seconds |             | $^\circ\text{C}$          |
| $\theta_{JC}$       | Junction-to-Case Thermal Resistance | 210                |             | $^\circ\text{C}/\text{W}$ |
| $P_{TOT}$           | Total Device Power Dissipation      | 200                |             | mW                        |
| <b>EMITTER</b>      |                                     |                    |             |                           |
| $I_F$               | Continuous Forward Current          | $\pm 50$           | 50          | mA                        |
| $V_R$               | Reverse Voltage                     |                    | 6           | V                         |
| $P_D$               | Power Dissipation                   | 70                 |             | mW                        |
|                     | Derate Above $100^\circ\text{C}$    | 1.7                |             | mW/ $^\circ\text{C}$      |
| <b>DETECTOR</b>     |                                     |                    |             |                           |
| $V_{CEO}$           | Collector-Emitter Voltage           | 70                 |             | V                         |
| $V_{ECO}$           | Emitter-Collector Voltage           | 6                  |             | V                         |
| $I_C$               | Continuous Collector Current        | 50                 |             | mA                        |
| $P_C$               | Collector Power Dissipation         | 150                |             | mW                        |
|                     | Derate Above $90^\circ\text{C}$     | 2.9                |             | mW/ $^\circ\text{C}$      |

## Electrical Characteristics

$T_A = 25^\circ\text{C}$  unless otherwise specified.

### Individual Component Characteristics

| Symbol          | Parameter                           | Device | Test Conditions                        | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------------|--------|--|------|------|------|---------------|
| <b>EMITTER</b>  |                                     |        |  |      |      |      |               |
| $V_F$           | Forward Voltage                     | FOD814 | $I_F = \pm 20\text{ mA}$               |      | 1.2  | 1.4  | V             |
|                 |                                     | FOD817 | $I_F = 20\text{ mA}$                   |      | 1.2  | 1.4  |               |
| $I_R$           | Reverse Current                     | FOD817 | $V_R = 4.0\text{ V}$                   |      |      | 10   | $\mu\text{A}$ |
| $C_t$           | Terminal Capacitance                | FOD814 | $V = 0, f = 1\text{ kHz}$              |      | 50   | 250  | pF            |
|                 |                                     | FOD817 | $V = 0, f = 1\text{ kHz}$              |      | 30   | 250  |               |
| <b>DETECTOR</b> |                                     |        |  |      |      |      |               |
| $I_{CEO}$       | Collector Dark Current              | FOD814 | $V_{CE} = 20\text{ V}, I_F = 0$        |      |      | 100  | nA            |
|                 |                                     | FOD817 | $V_{CE} = 20\text{ V}, I_F = 0$        |      |      | 100  |               |
| $BV_{CEO}$      | Collector-Emitter Breakdown Voltage | FOD814 | $I_C = 0.1\text{ mA}, I_F = 0$         | 70   |      |      | V             |
|                 |                                     | FOD817 | $I_C = 0.1\text{ mA}, I_F = 0$         | 70   |      |      |               |
| $BV_{ECO}$      | Emitter-Collector Breakdown Voltage | FOD814 | $I_E = 10\text{ }\mu\text{A}, I_F = 0$ | 6    |      |      | V             |
|                 |                                     | FOD817 | $I_E = 10\text{ }\mu\text{A}, I_F = 0$ | 6    |      |      |               |

### DC Transfer Characteristics

| Symbol        | Parameter                             | Device  | Test Conditions                              | Min. | Typ. | Max. | Unit |
|---------------|---------------------------------------|---------|--|------|------|------|------|
| CTR           | Current Transfer Ratio <sup>(2)</sup> | FOD814  | $I_F = \pm 1\text{ mA}, V_{CE} = 5\text{ V}$ | 20   |      | 300  | %    |
|               |                                       | FOD814A |  | 50   |      | 150  |      |
|               |                                       | FOD817  | $I_F = 5\text{ mA}, V_{CE} = 5\text{ V}$     | 50   |      | 600  |      |
|               |                                       | FOD817A |  | 80   |      | 160  |      |
|               |                                       | FOD817B |  | 130  |      | 260  |      |
|               |                                       | FOD817C |  | 200  |      | 400  |      |
|               |                                       | FOD817D |  | 300  |      | 600  |      |
| $V_{CE(SAT)}$ | Collector-Emitter Saturation Voltage  | FOD814  | $I_F = \pm 20\text{ mA}, I_C = 1\text{ mA}$  |      | 0.1  | 0.2  | V    |
|               |                                       | FOD817  | $I_F = 20\text{ mA}, I_C = 1\text{ mA}$      |      | 0.1  | 0.2  |      |

### AC Transfer Characteristics

| Symbol | Parameter            | Device         | Test Conditions   | Min. | Typ. | Max. | Unit          |
|--------|----------------------|----------------|---|------|------|------|---------------|
| $f_C$  | Cut-Off Frequency    | FOD814         | $V_{CE} = 5\text{ V}, I_C = 2\text{ mA}, R_L = 100\text{ }\Omega, -3\text{ dB}$ | 15   | 80   |      | kHz           |
| $t_r$  | Response Time (Rise) | FOD814, FOD817 | $V_{CE} = 2\text{ V}, I_C = 2\text{ mA}, R_L = 100\text{ }\Omega^{(3)}$         |      | 4    | 18   | $\mu\text{s}$ |
| $t_f$  | Response Time (Fall) | FOD814, FOD817 |   |      |      | 3    | 18            |

#### Notes:

- Current Transfer Ratio (CTR) =  $I_C / I_F \times 100\%$ .
- For test circuit setup and waveforms, refer to page 7.

**Electrical Characteristics** (Continued) $T_A = 25^\circ\text{C}$  unless otherwise specified.**Isolation Characteristics**

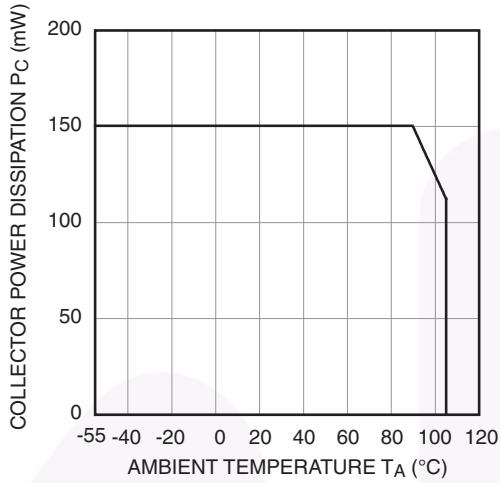
| Symbol           | Parameter                                     | Device            | Test Conditions   | Min.               | Typ.               | Max. | Unit                      |
|------------------|---|-------------------|---|--------------------|--------------------|------|---------------------------|
| $V_{\text{ISO}}$ | Input-Output Isolation Voltage <sup>(4)</sup> | FOD814,<br>FOD817 | $f = 60 \text{ Hz}$ , $t = 1 \text{ minute}$ ,<br>$I_{\text{I-O}} \leq 2 \mu\text{A}$ | 5000               |                    |      | $\text{VAC}_{\text{RMS}}$ |
| $R_{\text{ISO}}$ | Isolation Resistance                          | FOD814,<br>FOD817 | $V_{\text{I-O}} = 500 \text{ V}_{\text{DC}}$  | $5 \times 10^{10}$ | $1 \times 10^{11}$ |      | $\Omega$                  |
| $C_{\text{ISO}}$ | Isolation Capacitance                         | FOD814,<br>FOD817 | $V_{\text{I-O}} = 0$ , $f = 1 \text{ MHz}$  |                    | 0.6                | 1.0  | pf                        |

**Note:**

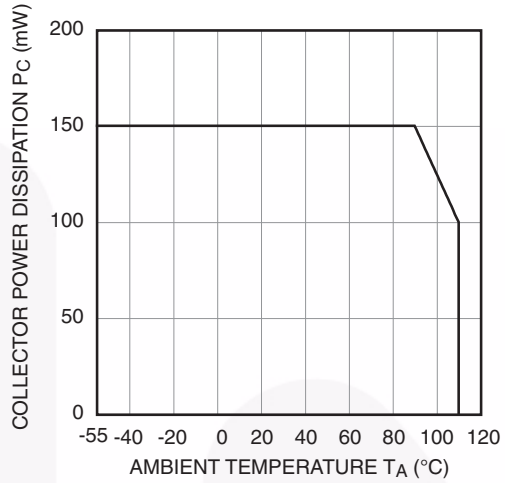
4. For this test, Pins 1 and 2 are common, and Pins 3 and 4 are common.

## Typical Electrical/Optical Characteristic Curves

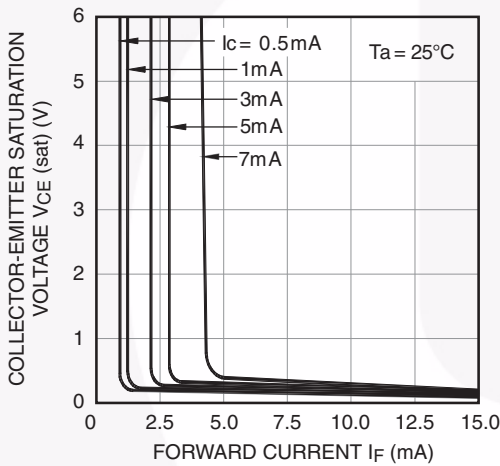
$T_A = 25^\circ\text{C}$  unless otherwise specified.



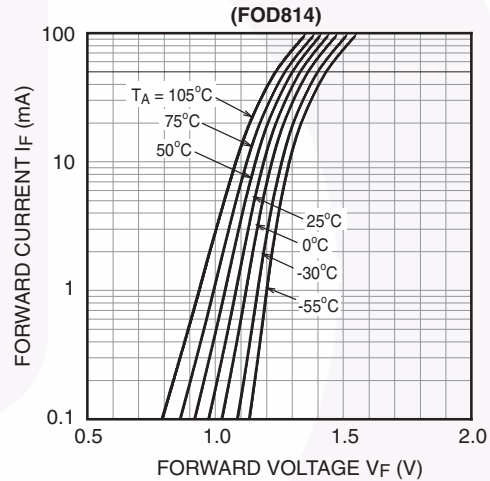
**Fig. 3 Collector Power Dissipation vs. Ambient Temperature (FOD814)**



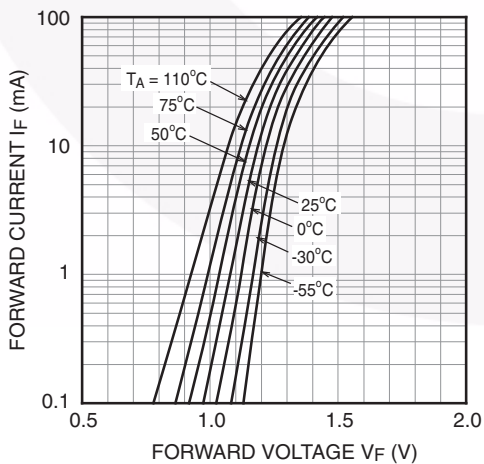
**Fig. 4 Collector Power Dissipation vs. Ambient Temperature (FOD817)**



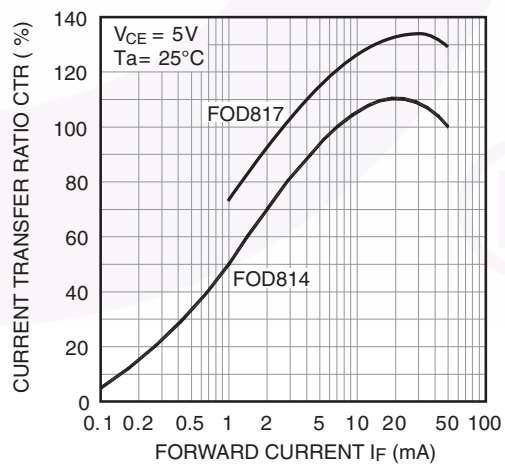
**Fig. 5 Collector-Emitter Saturation Voltage vs. Forward Current**



**Fig. 6 Forward Current vs. Forward Voltage**



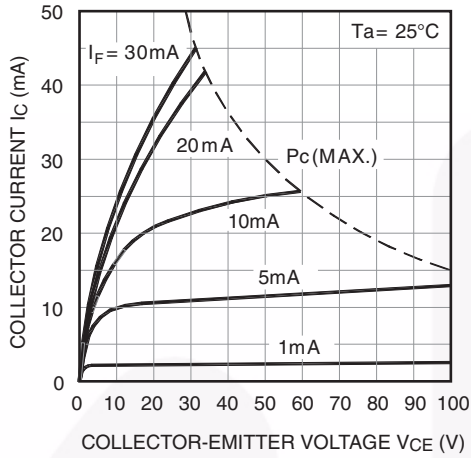
**Fig. 7 Forward Current vs. Forward Voltage (FOD817)**



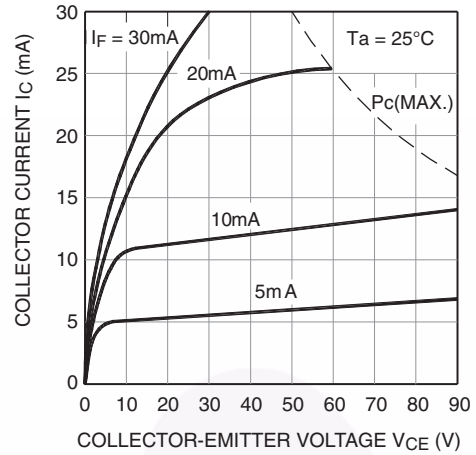
**Fig. 8 Current Transfer Ratio vs. Forward Current**

### Typical Electrical/Optical Characteristic Curves (Continued)

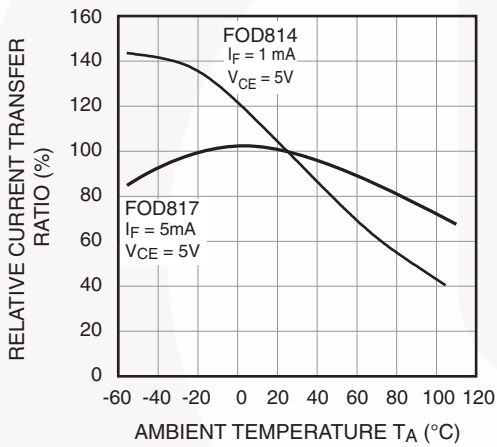
$T_A = 25^\circ\text{C}$  unless otherwise specified.



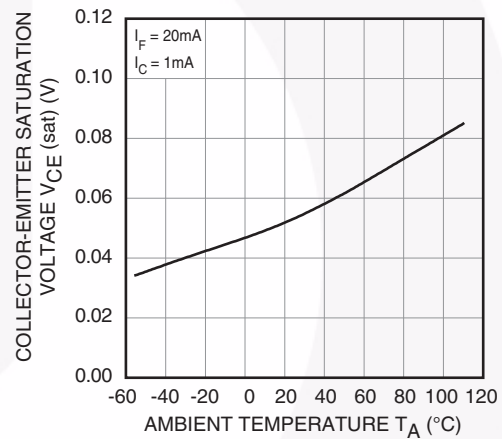
**Fig. 9 Collector Current vs. Collector-Emitter Voltage (FOD814)**



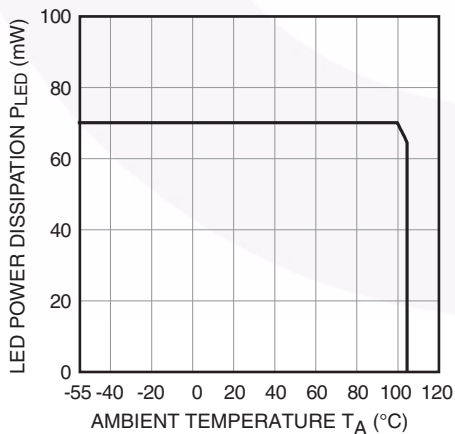
**Fig. 10 Collector Current vs. Collector-Emitter Voltage (FOD817)**



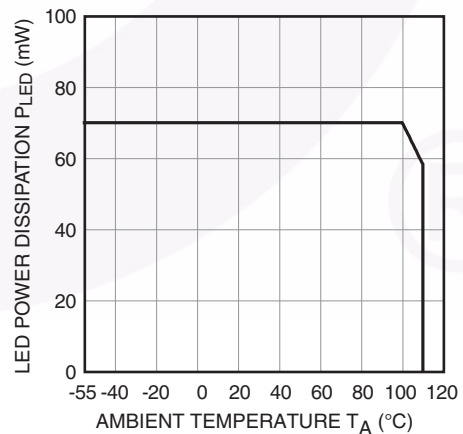
**Fig. 11 Relative Current Transfer Ratio vs. Ambient Temperature**



**Fig. 12 Collector-Emitter Saturation Voltage vs. Ambient Temperature**



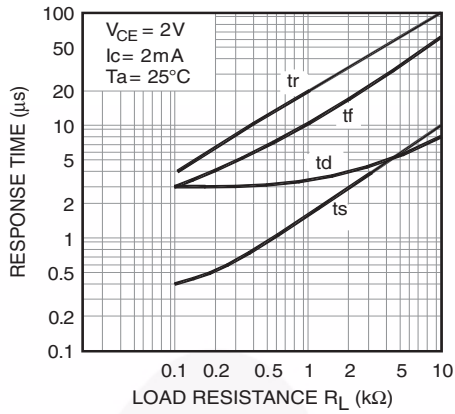
**Fig. 13 LED Power Dissipation vs. Ambient Temperature (FOD814)**



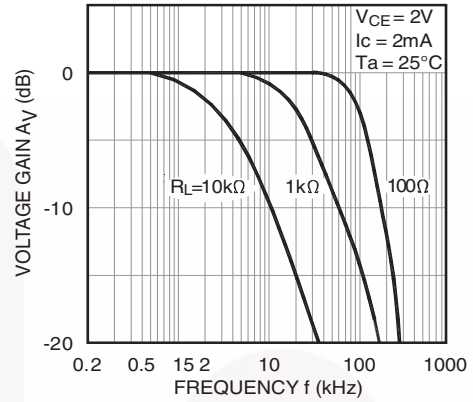
**Fig. 14 LED Power Dissipation vs. Ambient Temperature (FOD817)**

### Typical Electrical/Optical Characteristic Curves (Continued)

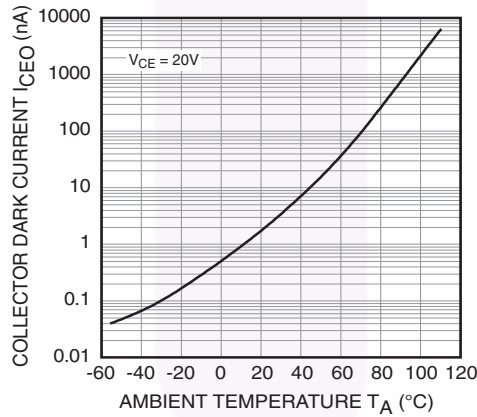
$T_A = 25^\circ\text{C}$  unless otherwise specified.



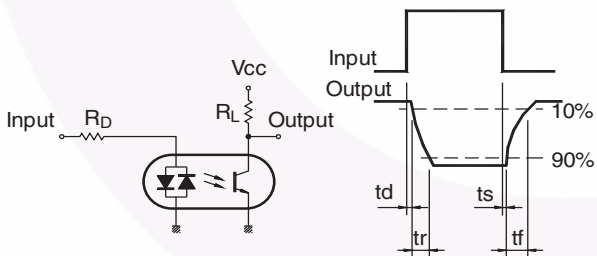
**Fig. 15 Response Time vs. Load Resistance**



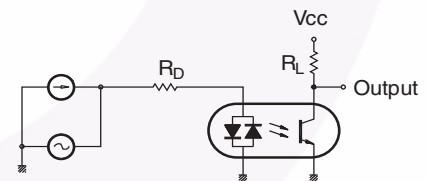
**Fig. 16 Frequency Response**



**Fig. 17 Collector Dark Current vs. Ambient Temperature**



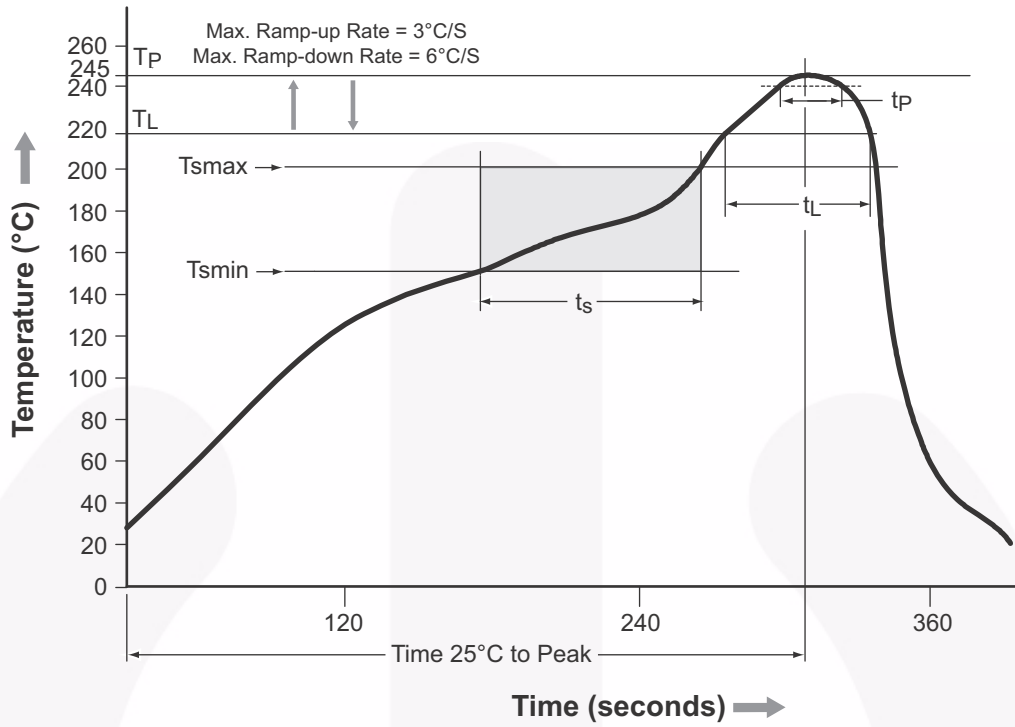
**Fig. 18 Test Circuit for Response Time**



**Fig. 19 Test Circuit for Frequency Response**



### Reflow Profile



| Profile Feature   | Pb-Free Assembly Profile |
|---|--------------------------|
| Temperature Min. (T <sub>smin</sub> )                                 | 150°C                    |
| Temperature Max. (T <sub>smax</sub> )                                 | 200°C                    |
| Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> ) | 60–120 seconds           |
| Ramp-up Rate (t <sub>L</sub> to t <sub>p</sub> )                      | 3°C/second max.          |
| Liquidous Temperature (T <sub>L</sub> )                               | 217°C                    |
| Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )             | 60–150 seconds           |
| Peak Body Package Temperature   | 245°C +0°C / -5°C        |
| Time (t <sub>p</sub> ) within 5°C of 260°C                            | 30 seconds               |
| Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )                    | 6°C/second max.          |
| Time 25°C to Peak Temperature   | 8 minutes max.           |

Figure 20. Reflow Profile

## Ordering Information

| Part Number | Package  | Packing Method                       |
|-------------|--|--------------------------------------|
| FOD817X     | DIP 4-Pin  | Tube (100 units per tube)            |
| FOD817XS    | SMT 4-Pin (Lead Bend)                                    | Tube (100 units per tube)            |
| FOD817XSD   | SMT 4-Pin (Lead Bend)                                    | Tape and Reel (1,000 units per reel) |
| FOD817X300  | DIP 4-Pin, DIN EN/IEC60747-5-5 option                    | Tube (100 units per tube)            |
| FOD817X3S   | SMT 4-Pin (Lead Bend), DIN EN/IEC60747-5-5 option        | Tube (100 units per tube)            |
| FOD817X3SD  | SMT 4-Pin (Lead Bend), DIN EN/IEC60747-5-5 option        | Tape and Reel (1,000 units per reel) |
| FOD817X300W | DIP 4-Pin, 0.4" Lead Spacing, DIN EN/IEC60747-5-5 option | Tube (100 units per tube)            |

### Note:

The product orderable part number system listed in this table also applies to the FOD814 products.

"X" denotes the Current Transfer Ratio (CTR) options

## Marking Information

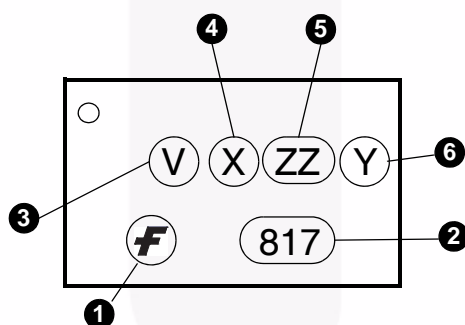


Figure 21. Top Mark

| Definitions |   |
|-------------|---|
| 1           | Fairchild Logo  |
| 2           | Device Number   |
| 3           | DIN EN/IEC60747-5-5 Option (only appears on parts ordered with this option)         |
| 4           | One-Digit Year Code, e.g., '5'  |
| 5           | Two-Digit Work Week, Ranging from '01' to '53'                                      |
| 6           | Assembly Package Code<br>Y = Manufactured in Thailand<br>YA = Manufactured in China |

### Carrier Tape Specifications

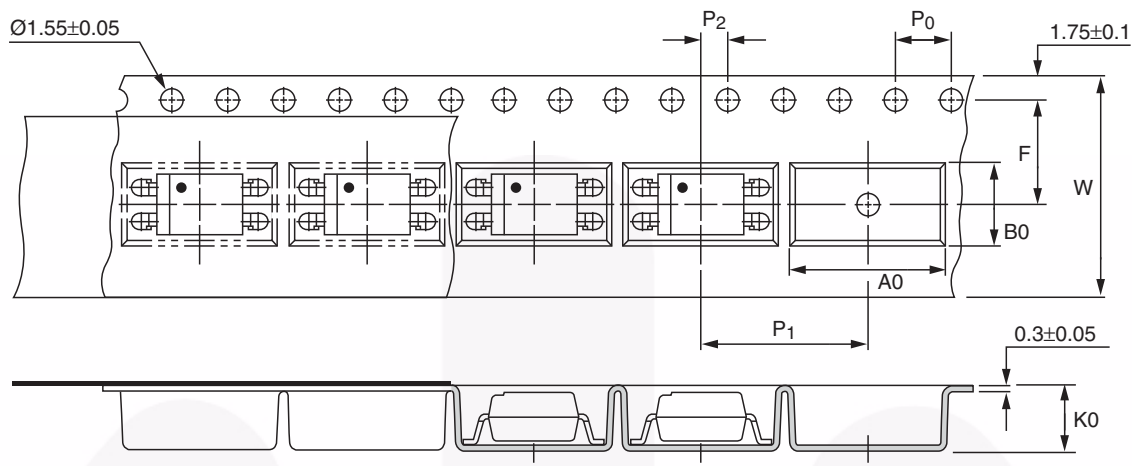
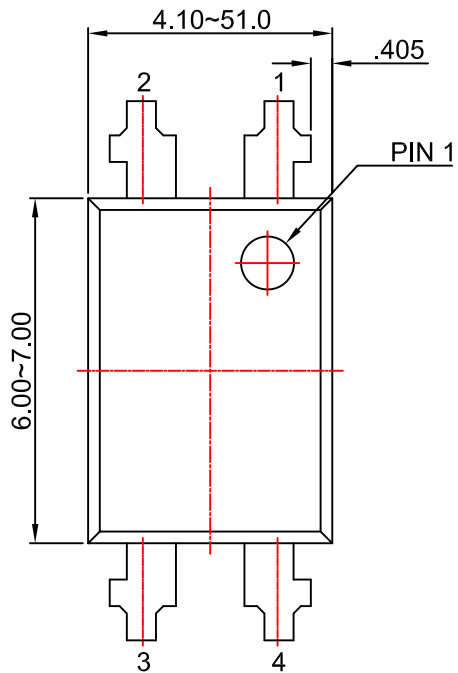


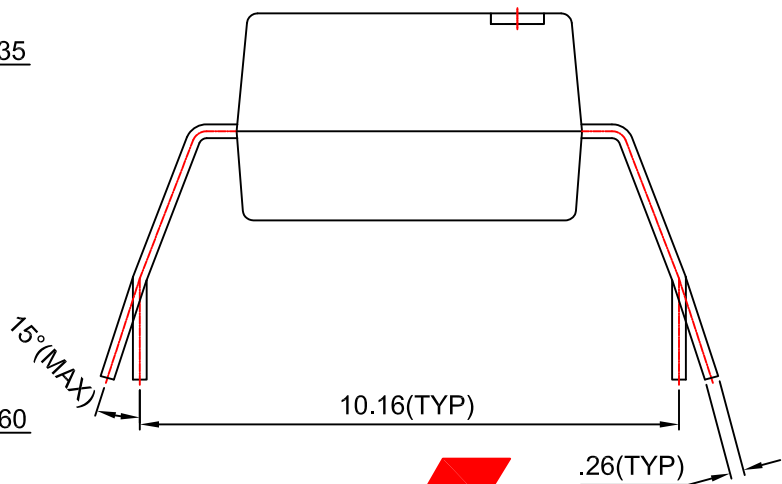
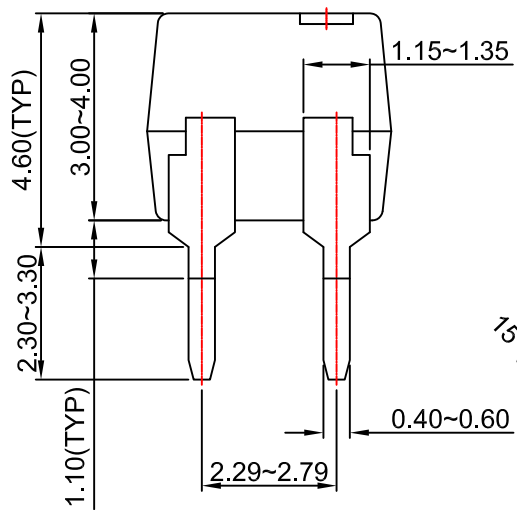
Figure 22. Carrier Tape Specification

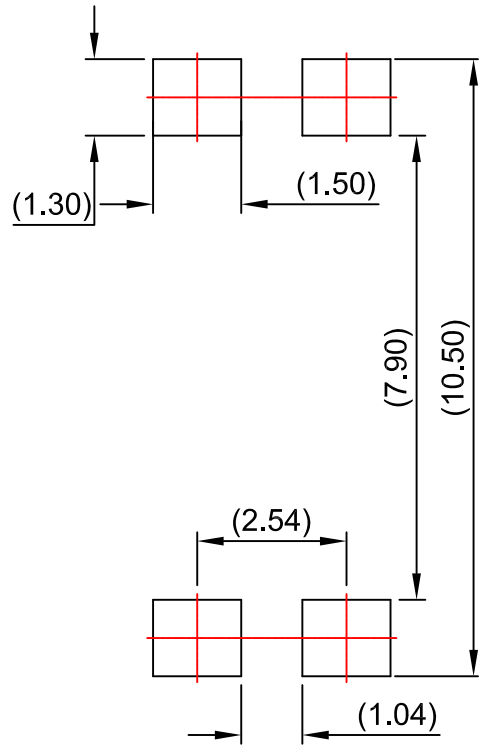
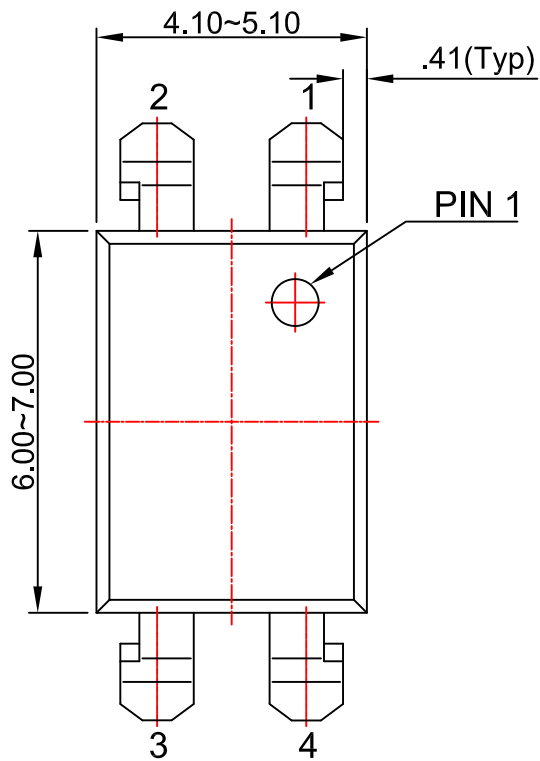
| Symbol     | Description                            | Dimensions in mm (inches)                    |
|------------|--|--|
| W          | Tape wide                              | $16 \pm 0.3$ (0.63)                          |
| $P_0$      | Pitch of sprocket holes                | $4 \pm 0.1$ (0.15)                           |
| F<br>$P_2$ | Distance of compartment                | $7.5 \pm 0.1$ (0.295)<br>$2 \pm 0.1$ (0.079) |
| $P_1$      | Distance of compartment to compartment | $12 \pm 0.1$ (0.472)                         |
| A0         | Compartment                            | $10.45 \pm 0.1$ (0.411)                      |
| B0         |  | $5.30 \pm 0.1$ (0.209)                       |
| K0         |  | $4.25 \pm 0.1$ (0.167)                       |



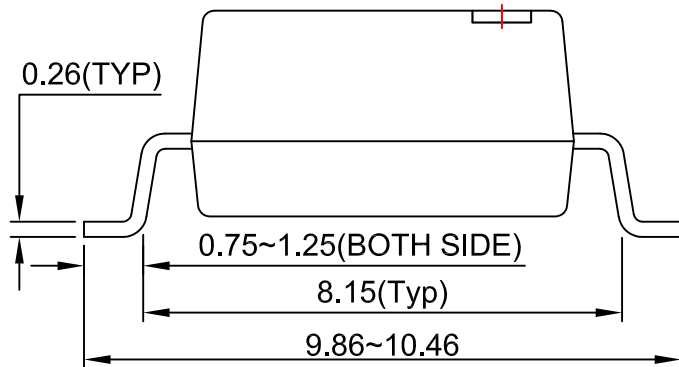
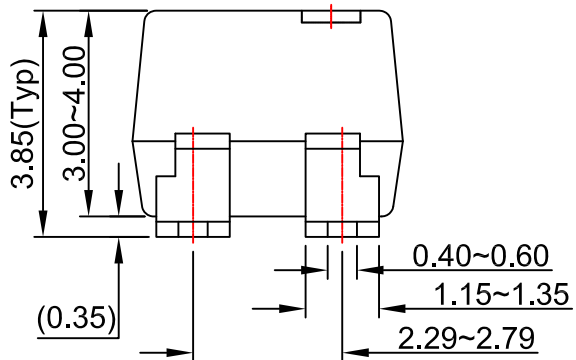
NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N04Brev2.





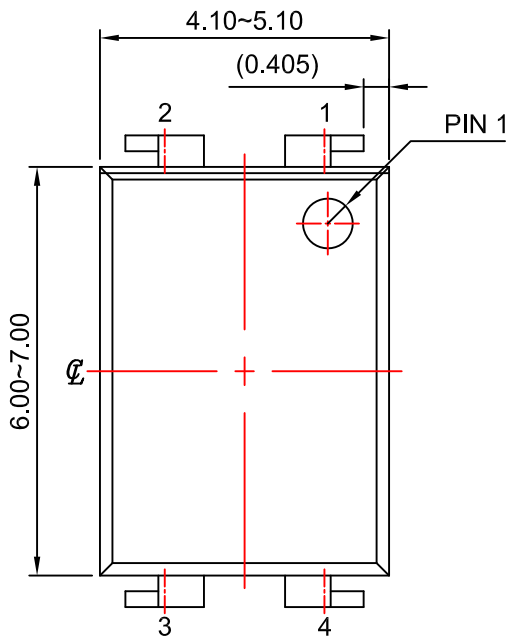
LAND PATTERN RECOMMENDATION



NOTES:

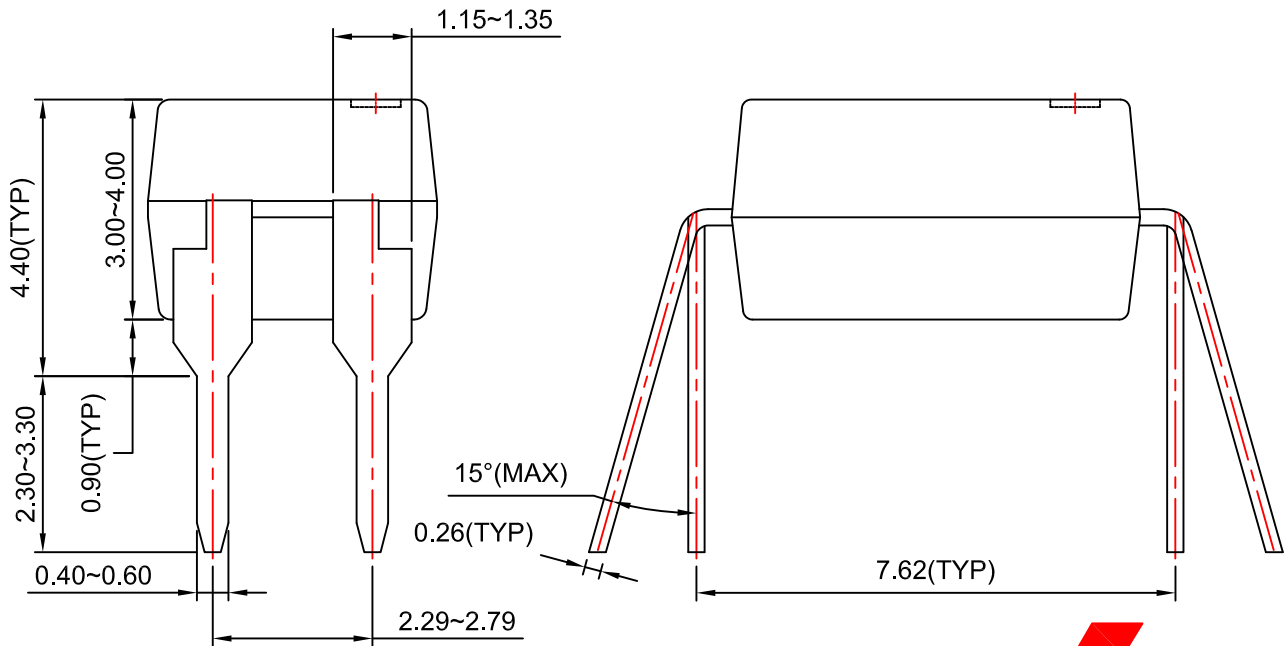
- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N04Crev2.





NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION
- D) DRAWING FILENAME AND REVISION: MKT-N04Arev2.





**TRADEMARKS**

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™  
AttitudeEngine™  
Awinda®  
AX-CAP®\*  
BitSiC™  
Build it Now™  
CorePLUS™  
CorePOWER™  
CROSSVOL™  
CTL™  
Current Transfer Logic™  
DEUXPEED®  
Dual Cool™  
EcoSPARK®  
EfficientMax™  
ESBC™  
F®  
Fairchild®  
Fairchild Semiconductor®  
FACT Quiet Series™  
FACT®  
FastvCore™  
FETBench™  
FPS™

F-PFS™  
FRFET®  
Global Power Resource™  
GreenBridge™  
Green FPS™  
Green FPS™ e-Series™  
Gmax™  
GTO™  
IntelliMAX™  
ISOPLANAR™  
Making Small Speakers Sound Louder and Better™  
MegaBuck™  
MICROCOUPLER™  
MicroFET™  
MicroPak™  
MicroPak2™  
MillerDrive™  
MotionMax™  
MotionGrid®  
MTi®  
MTx®  
MVN®  
mWSaver®  
OptoHiT™  
OPTOLOGIC®

OPTOPLANAR®  
Power Supply WebDesigner™  
PowerTrench®  
PowerXS™  
Programmable Active Droop™  
QFET®  
QS™  
Quiet Series™  
RapidConfigure™  
Saving our world, 1mW/W/kW at a time™  
SignalWise™  
SmartMax™  
SMART START™  
Solutions for Your Success™  
SPM®  
STEALTH™  
SuperFET®  
SuperSOT™-3  
SuperSOT™-6  
SuperSOT™-8  
SupreMOS®  
SyncFET™  
Sync-Lock™

SYSTEM GENERAL®  
TinyBoost®  
TinyBuck®  
TinyCalc™  
TinyLogic®  
TINYOPTO™  
TinyPower™  
TinyPWM™  
TinyWire™  
TranSiC™  
TriFault Detect™  
TRUECURRENT®\*  
µSerDes™  
SerDes®  
UHC®  
Ultra FRFET™  
UniFET™  
VCX™  
VisualMax™  
VoltagePlus™  
XS™  
Xsens™  
仙童®

\* Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

**DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT [HTTP://WWW.FAIRCHILDSEMI.COM](http://www.fairchildsemi.com). FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

**AUTHORIZED USE**

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

**ANTI-COUNTERFEITING POLICY**

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, [www.fairchildsemi.com](http://www.fairchildsemi.com), under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

**PRODUCT STATUS DEFINITIONS**

**Definition of Terms**

| Datasheet Identification | Product Status        | Definition  |
|--------------------------|-----------------------|---|
| Advance Information      | Formative / In Design | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.   |
| Preliminary              | First Production      | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production       | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.   |
| Obsolete                 | Not In Production     | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.  |